ONE-STOP SUPPLIER OF SEMICONDUCTOR CARRIER PRODUCTS

Hiner-pack® MHWJ Canister 150 mm

Engineered for safe handling of delicate wafers during shipping and storage

Designed for cost-effective wafer handling, these polypropylene wafer jars are ideal for storing and transporting multiple non-sensitive wafers. The secure lid prevents accidental opening, while internal separators, foam disks, and liner foam walls create a multi-layer protective barrier against mechanical shock, vibration, and direct wafer contact. Available in 150mm and 200mm options, with customized sizes on request, and in clear, white, or black for visual inspection or ESD-safe applications. Their stackable, reusable design makes them an efficient cleanroom storage solution, reducing packaging waste. From semiconductor fabrication plants to wafer distribution, these wafer jars deliver reliable protection and contamination control throughout the process.



SPECIFICATIONS

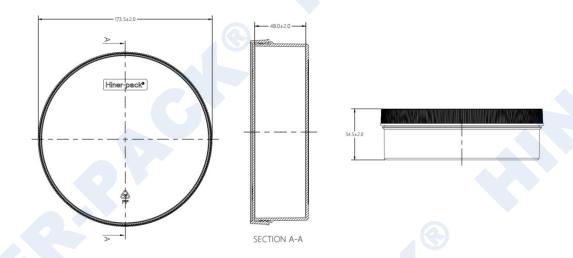
- 173.5 mm L × 173.5 mm W × 54.5 mm H (6.83" × 6.83" × 2.15")
- Maximum load capacity is 25 pieces
- · Sold in full case quantity (81)

FEATURES & BENEFITS

- Interleaf separators prevent direct wafer surface contact
- Foam liners and cushion disks absorb shocks and vibration
- The bottom and the top cover are designed to facilitate the operator to open and ensure safety during transportation



DIMENSION



BASIC INFORMATION

| Part Number | Collocation Reference | Wafer Size |
|---------------------|---------------------------------|------------|
| MHWJ-6/25-160/48-WH | Bottom+Foam+Interleaf+Liner+Top | 150 mm |

REFERENCE ILLUSTRATION



The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

| PROPERTY | TEST METHOD | RATED VALUES |
|-----------------------------|----------------------|-----------------------|
| Density | ISO 1183 | 0.9 g/cm ³ |
| Melt Index | ISO 1133 | 15 g/10min |
| Melting Point | DSC | 146°C |
| Distortion Temperature | ISO 75 | 95°C |
| Vicat softening temperature | ISO 306 | 125°C |
| Tensile Strength at Yield | ISO 527 | 280 kg/m² |
| Tensile Elongation at Break | ISO 527 | 300 % |
| Rockwell hardness R scale | ISO 2039 | 98 |
| Tensile Strain at Break | ISO 527-2 (50mm/min) | 10 % |
| Flexural Modulus | ISO 178 | 10500 kg/m² |
| Flow Shrinkage | FPC Method | 1.3~1.7 % |
| LZOD Impact Strength | 23°C ISO 180 | 6 kg.cm/cm |
| | -20°C | notch |

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.



Corporate Headquarters

Bldg A11, Zone D, West Industrial Zone, Minzhu Comm., Shajing St., Bao'an, Shenzhen, Guangdong, China

Customer Service

Tel +86 755 2322 9236 Fax +86 755 2996 0455

Work Time 08:00 - 18:00 (Beijing Time/UTC+8)

 $\label{eq:hiner-pack} \mbox{Hiner-pack$^{\otimes}$ is a registered trademark of Shenzhen Hiner Technology Co., Ltd.}$

©2013-2025 Shenzhen Hiner Technology Co., Ltd. | All rights reserved.